

Stencil cleaner – ready-to-use

SYS-CLEAN® STC1.0 is a water-based cleaning medium for cleaning SMT stencils already at room temperature.

SYS-CLEAN® STC1.0 reliably cleans solder pastes from stencils and misprints. The cleaner can be used in spray processes as well as in immersion or ultrasonic systems will be.



Application

Pollution	Suitability
Solder pastes	✓ ✓
SMT adhesive or conductive adhesive	✓
Flux	✓
Oils/fats	✓

Application parameters

Parameter	
Application temperature	20°C
Cleaning duration approx.	4-6 min.
Rinsing	STC1.0 / DI-Water
Drying	convection / compressed air
Application Concentration	ready-to-use

✓ ✓ = Excellent ✓ = Optimal ○ = Optional ✗ = Not recommended

Specifications

SYS-CLEAN® STC1.0 is delivered as a ready-to-use mix.

pH-Value	7,7
Density (at 20°C)	0,9995 g/cm ³
Refractive Index (at 20°C)	1,3522
Initial boiling point and boiling range	>100 °C
Flashpoint	n. A.

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Application	
Spray-in-air	✓ ✓
Immersion cleaning air agitated	✓ ✓
Spray under Immersion	✓ ✓
Ultrasonic	✓ ✓
Manual cleaning	✓

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Advantages:

SYS-CLEAN® STC1.0 is very well filterable and has an optimized discharge behaviour which reduces consumption and prevents oily residues. The high loading capacity ensures a particularly cost-effective process.

Since the medium does not separate, use in underside cleaning is possible without problems.

Availability:

SYS-CLEAN® STC1.0 Ready-to-use is available in the following sizes

Item number: 64904042 – 1L

Item number: 64903565 – 5L

Item number: 64903511 – 25L

Item number: 64903512 – 200L



The product is free of questionable ingredients according to the SIN- & SVHC-Lists



100% compliant with EU guidelines RoHS 1 & 2, WEEE